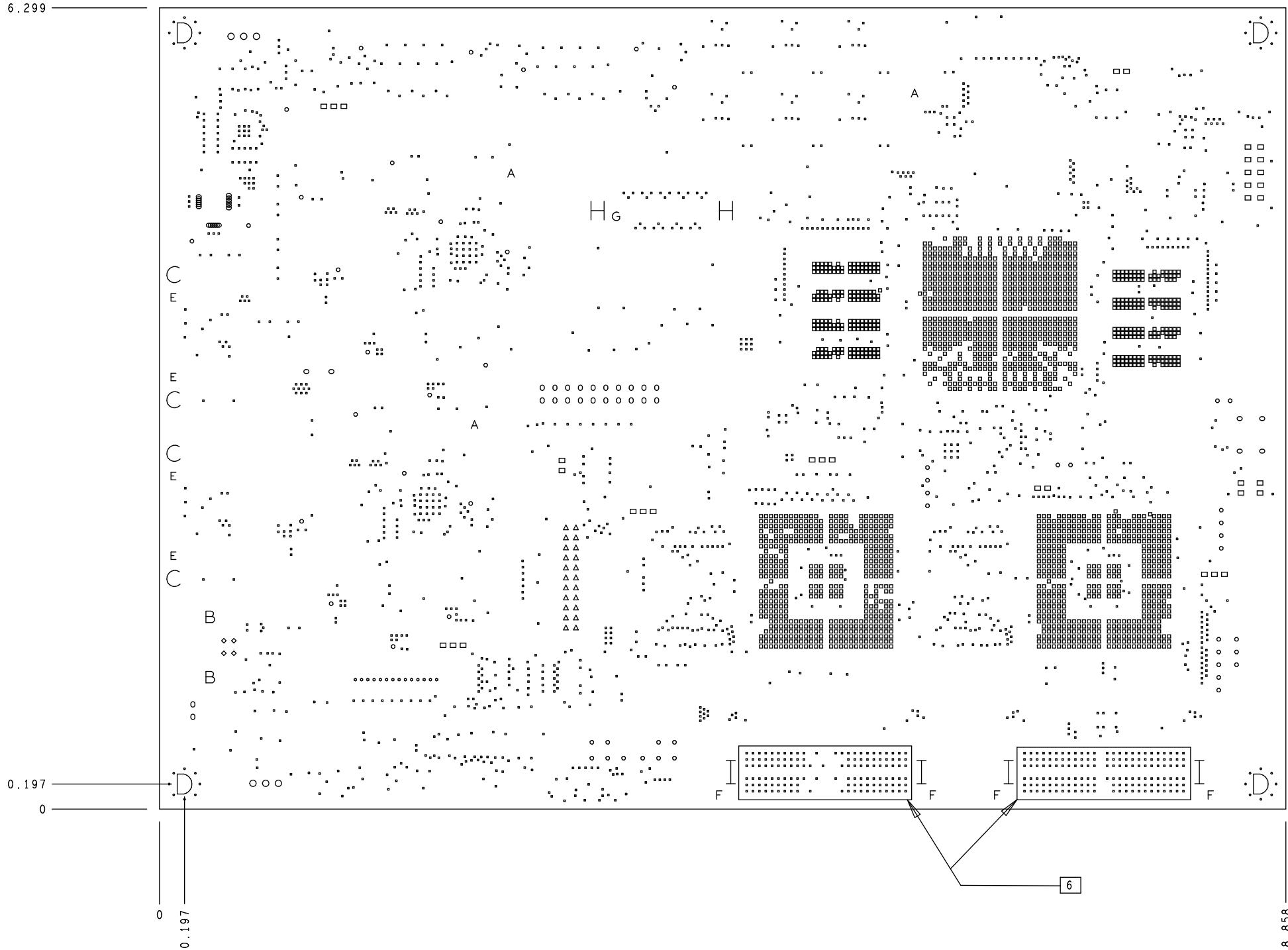


DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
▪	8.0	+3.0/-8.0	PLATED	2097
•	12.0	+3.0/-12.0	PLATED	2024
•	14.0	+3.0/-3.0	PLATED	32
•	20.0	+3.0/-3.0	PLATED	14
◦	28.0	+3.0/-3.0	PLATED	53
◦	36.0	+3.0/-3.0	PLATED	4
△	38.0	+3.0/-1.0	PLATED	22
◦	40.0	+2.0/-2.0	PLATED	24
◦	42.0	+3.0/-3.0	PLATED	22
▣	45.0	+3.0/-3.0	PLATED	35
◦	50.0	+3.0/-3.0	PLATED	6
A	63.0	+3.0/-3.0	PLATED	3
B	90.0	+3.0/-3.0	PLATED	2
C	126.0	+3.0/-3.0	PLATED	4
D	157.0	+3.0/-3.0	PLATED	4
E	59.0	+3.0/-3.0	NON-PLATED	4
F	66.0	+3.0/-3.0	NON-PLATED	4
G	67.008	+3.0/-3.0	NON-PLATED	1
H	147.008	+3.0/-3.0	NON-PLATED	2
I	182.0	+3.0/-3.0	NON-PLATED	4

6.299



Primary Side Shown



TEXAS INSTRUMENTS		
BOARD NAME: DDP4422 DUAL ASIC FORMATTER	DESCRIPTION: FAB DRAWING	
PROJECT #: TIDL P-23791-03	DATE: 01 OCT 2015	REVISION: 21

FAB NOTES:

- ALL DIMENSIONS ARE IN INCHES. UNLESS OTHERWISE SPECIFIED, ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010".
- THE PWB SHALL BE FABRICATED TO IPC-6011 AND IPC-6012, CLASS 2, TYPE 3. WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
- BOARD MATERIAL SHALL BE 180 Ig/340 Td ISOLA FR-370HR OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. RoHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.
- BOARD MATERIAL & CONSTRUCTION TO BE U.L. APPROVED AND MARKED ON THE FINISHED BOARD.
- MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH WITH A MINIMUM ANNULAR RING OF .001 INCH.
- OVERALL BOARD THICKNESS TO BE .070 +/- .005 AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
- INNER PLANE LAYERS TO BE 1 OZ. COPPER. INNER SIGNAL LAYERS TO BE 1/2 OZ. COPPER. OUTER LAYERS TO BE 1/2 OZ. COPPER + PLATING.
- MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
- ALL HOLES ARE ON A 0.0001 GRID EXCEPT THOSE INDICATED.
- MAXIMUM RATED VOLTAGE BETWEEN CONDUCTORS SHALL BE 65 VOLTS PEAK.
- NO BREAKOUT ALLOWED ON PLATED THROUGH HOLES.
- FOIL OUTER OPTIONAL.
- INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994
- TEARDROP VIAS AS NECESSARY.
- THIEVING IS NOT ALLOWED.

PROCESS NOTES:

- EXCEPT AS NOTED BELOW, ALL EXPOSED CONDUCTORS ON BOTH SIDES PWB SHALL BE ELECTROPLATED GOLD (5-15 MICROINCHES) OVER ELECTROPLATED NICKEL (150 MIN MICROINCHES).
- APPLY LPI SOLDERMASK. COLOR: BLUE. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
- SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS. FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
- APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.
- BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
- PLATE INDICATED PAD AREAS WITH A MINIMUM OF 35 MAXIMUM OF 50 MICROINCHES ELECTROLYTIC HARD GOLD OVER A MINIMUM OF 100 MICROINCHES OF ELECTROLYTIC NICKEL.

LAYER STACKUP

LAYER 1 - PRIMARY SIDE
LAYER 2 - GND PLANE
LAYER 3 - SIGNAL
LAYER 4 - GND PLANE
LAYER 5 - SIGNAL
LAYER 6 - GND PLANE
LAYER 7 - PWR PLANE
LAYER 8 - PWR PLANE
LAYER 9 - GND PLANE
LAYER 10 - SIGNAL
LAYER 11 - GND PLANE
LAYER 12 - SIGNAL
LAYER 13 - GND PLANE
LAYER 14 - SIGNAL

CONTROLLED IMPEDANCE

EXTERNAL LAYERS
0.005" WIDE 50 OHMS SINGLE ENDED +/-10%
0.0038" WIDE/0.0062" SPACING 100 OHMS DIFFERENTIAL +/-10%
0.0045" WIDE/0.0055" SPACING 90 OHMS DIFFERENTIAL +/-10%

INTERNAL LAYERS
0.004" WIDE 50 OHMS SINGLE ENDED +/-10%
0.0035" WIDE/0.0065" SPACING 100 OHMS DIFFERENTIAL +/-10%
0.00425" WIDE/0.00575" SPACING 90 OHMS DIFFERENTIAL +/-10%